

Professional Development Course: Advanced Packaging Technologies and Methodologies for Compound Semiconductors

See the full agenda of Advanced Packaging Technologies and Methodologies for CS below, delivered to you by Andy Longford C.Eng FIET - CSA Catapult Packaging Strategy Consultant:

**Day 1:**

Session 1: Packaging Overview

- Overview of the needs for packaging and trends for the future
- Review of the packaging process steps

Session 2: Packaging the Applications – RF, Photonics & Power

- Review of general packaging needs
- A review of the direction and needs of Power packaging
- A review of the direction and needs of RF packaging
- A review of the direction and needs of Photonics packaging

Session 3: The Essentials for Packaging

- Die and substrate preparation
- Die attach approaches
- Defining the interconnections (flip chip/wirebond)

Session 4: The Package Build

- Package assembly/encapsulation
- QA/QC testing

**Day 2:**

Session 1: Die Attach and Sintering

Session 2: Working with Die attach

- Interactive session with Q&A
- Live demonstrations of CSA Catapult capability
- Tour of CSA Catapult labs (Photonics, RF, Power)

### Session 3: Wire bonding

### Session 4: Working with Wire bonds

- Interactive session for Q&A
- Live demonstrations of CSAC capability



Advanced Packaging Laboratory at CSA Catapult